MOSEL VITELIC

V61C5181024 128K X 8 HIGH SPEED STATIC RAM

Features

- High-speed: 10, 12, 15 ns
- Fully static operation
- All inputs and outputs directly TTL compatible
- Three state outputs
- Low data retention current ($V_{CC} = 2V$)
- Single 5V ± 10% Power Supply
- Low CMOS Standby current of 5 mA max

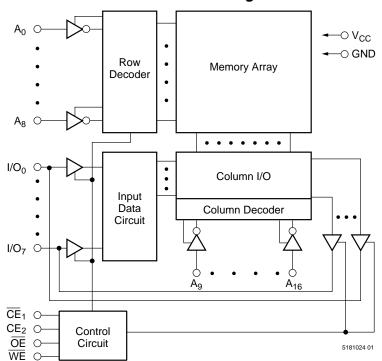
■ Packages

- 32-pin TSOP
- 32-pin 300 mil SOJ

Description

The V61C5181024 is a 1,048,576-bit static random-access memory organized as 131,072 words by 8 bits. Inputs and three-state outputs are TTL compatible and allow for direct interfacing with common system bus structures. The V61C5181024 is available in 32-pin SOJ, PDIP and TSOP.

Functional Block Diagram



Device Usage Chart

Operating	Package	Outline	A	ccess Time (n	s)	Tomporative
Temperature Range	Т	R	10	12	15	Temperature Mark
0°C to 70°C	•	•	•	•	•	Blank

Pin Descriptions

A₀-A₁₆ Address Inputs

These 17 address inputs select one of the 128K x 8 bit segments in the RAM.

CE₁, CE₂ Chip Enable Inputs

CE₁ is active LOW and CE₂ is active HIGH. Both chip enables must be active to read from or write to the device. If either chip enable is not active, the device is deselected and is in a standby power mode. The I/O pins will be in the high-impedance state when deselected.

OE Output Enable Input

The Output Enable input is active LOW. When \overline{OE} is LOW with \overline{CE} LOW and \overline{WE} HIGH, data of the selected memory location will be available on the I/O pins. When \overline{OE} is HIGH, the I/O pins will be in the high impedance state.

WE Write Enable Input

An active LOW input, \overline{WE} input controls read and write operations. When \overline{CE} and \overline{WE} inputs are both LOW, the data present on the I/O pins will be written into the selected memory location.

I/O₀-I/O₇ Data Input and Data Output Ports

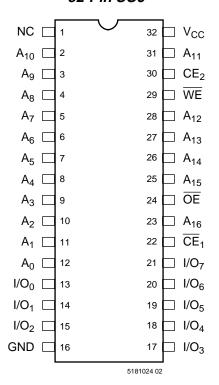
These 8 bidirectional ports are used to read data from and write data into the RAM.

V_{CC} Power Supply

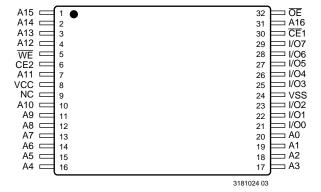
GND Ground

Pin Configurations (Top View)

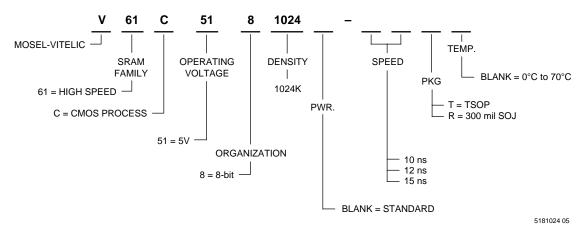
32-Pin SOJ



32-Pin TSOP-I (Standard)



Ordering Information



Absolute Maximum Ratings (1)

Symbol	Parameter	Commercial	Units
V _{CC}	Supply Voltage	-0.5 to +7	V
V _N	Input Voltage	-0.5 to +7	V
V _{DQ}	Input/Output Voltage Applied	V _{CC} + 0.5	V
T _{BIAS}	Temperature Under Bias	-10 to +125	°C
T _{STG}	Storage Temperature	-65 to +150	°C

NOTE:

Capacitance*

 $T_A = 25^{\circ}C$, f = 1.0MHz

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{OUT}	Output Capacitance	V _{I/O} = 0V	8	pF

NOTE:

1. This parameter is guaranteed by design and not tested.

Truth Table

Mode	CE ₁	CE ₂	ŌĒ	WE	I/O Operation
Standby	Н	Х	Х	Х	High Z
Standby	Х	L	Х	Х	High Z
Output Disable	L	Н	Н	Н	High Z
Read	L	Н	L	Н	D _{OUT}
Write	L	Н	Х	L	D _{IN}

NOTE:

X = Don't Care, L = LOW, H = HIGH

Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a
stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational
sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics (over all temperature ranges, $V_{CC} = 5V \pm 10\%$)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _{IL}	Input LOW Voltage ^(1,2)		-0.5	_	0.8	V
V _{IH}	Input HIGH Voltage ⁽¹⁾		2.2	_	6	V
I _{IL}	Input Leakage Current	$V_{CC} = Max$, $V_{IN} = 0V$ to V_{CC}	-5	_	5	μΑ
I _{OL}	Output Leakage Current	$V_{CC} = Max, \overline{CE}_1 = V_{IH}, V_{OUT} = 0V \text{ to } V_{CC}$	-5	_	5	μА
V _{OL}	Output LOW Voltage	V _{CC} = Min, I _{OL} = 2.1mA	_	_	0.4	V
V _{OH}	Output HIGH Voltage	V _{CC} = Min, I _{OH} = -1mA	2.4	_	_	V

Symbol	Parameter	Com. ⁽⁴⁾	Ind. ⁽⁴⁾	Units
I _{CC1}	Average Operating Current, $\overline{CE}_1 = V_{IL}$, $CE_2 = V_{IH}$, Output Open, $V_{CC} = Max.$, $f = f_{MAX}^{(3)}$	130	140	mA
I _{SB}	TTL Standby Current $\overline{CE}_1 \ge V_{IH}$, $CE_2 \le V_{IL}$, $V_{CC} = Max$.	35	40	mA
I _{SB1}	CMOS Standby Current, $\overline{CE}_1 \ge V_{CC} - 0.2V$, $CE_2 \le 0.2V$, $V_{IN} \ge V_{CC} - 0.2V$ or $V_{IN} \le 0.2V$, $V_{CC} = Max$.	5	6	mA

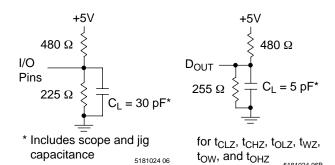
NOTES:

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. V_{IL} (Min.) = -3.0V for pulse width < 20ns.
- $3. \quad f_{MAX} = 1/t_{RC}.$
- 4. Maximum values.

AC Test Conditions

Input Pulse Levels	0 to 3V
Input Rise and Fall Times	3 ns
Timing Reference Levels	1.5V
Output Load	see below

AC Test Loads and Waveforms



Key to Switching Waveforms

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE: ANY CHANGE PERMITTED	CHANGING: STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

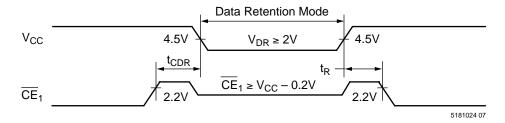
Data Retention Characteristics

Symbol	Parameter	Min.	Typ. ⁽²⁾	Max.	Units
V_{DR}	V_{CC} for Data Retention $\overline{CE}_1 \ge V_{CC} - 0.2V$, $CE_2 \le 0.2V$, $V_{IN} \ge V_{CC} - 0.2V$, or $V_{IN} \le 0.2V$	2.0		5.5	V
I _{CCDR}	Data Retention Current $\overline{CE}_1 \ge V_{DR} - 0.2V$, $CE_2 \le 0.2V$, $V_{IN} \ge V_{CC} - 0.2V$, or $V_{IN} \le 0.2V$	_	_	150	μΑ
t _{CDR}	Chip Deselect to Data Retention Time	0	_	_	ns
t _R	Operation Recovery Time (see Retention Waveform)	t _{RC} ⁽¹⁾	_	_	ns

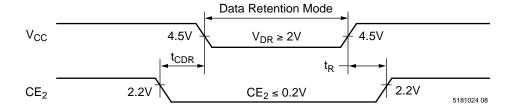
NOTES:

1. t_{RC} = Read Cycle Time 2. T_A = +25°C.

Low V_{CC} Data Retention Waveform (1) (CE₁ Controlled)



Low V_{CC} Data Retention Waveform (2) (CE₂ Controlled)



AC Electrical Characteristics

(over all temperature ranges)

Read Cycle

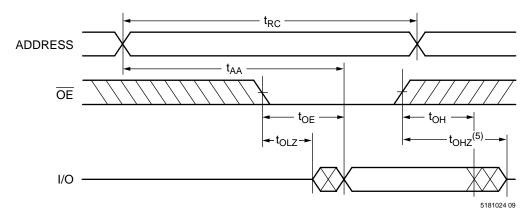
Parameter		-1	-10		12	-15		
Name	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
t _{RC}	Read Cycle Time	10	_	12	_	15	_	ns
t _{AA}	Address Access Time	_	10	_	12	_	15	ns
t _{ACS1}	Chip Enable Access Time	_	10	_	12	_	15	ns
t _{ACS2}	Chip Enable Access Time	_	10	_	12	_	15	ns
t _{OE}	Output Enable to Output Valid	_	6	_	6	_	7	ns
t _{CLZ1}	Chip Enable to Output in Low Z	3	_	3	_	3	_	ns
t _{CLZ2}	Chip Enable to Output in Low Z	3	_	3	_	3	_	ns
t _{OLZ}	Output Enable to Output in Low Z	0	_	0	_	0	_	ns
t _{CHZ}	Chip Disable to Output in High Z	0	3	0	3	0	4	ns
t _{OHZ}	Output Disable to Output in High Z	0	3	0	3	0	4	ns
t _{OH}	Output Hold from Address Change	3	_	3	_	3	_	ns

Write Cycle

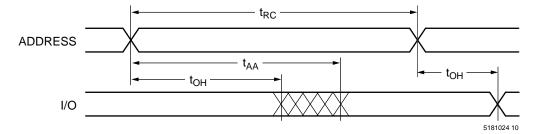
Parameter		-10		-1	2	-15		
Name	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
t _{WC}	Write Cycle Time	10	_	12	_	15	_	ns
t _{CW1}	Chip Enable to End of Write	8	_	10	_	13	_	ns
t _{CW2}	Chip Enable to End of Write	8	_	10	_	13	_	ns
t _{AS}	Address Setup Time	0	_	0	_	0	_	ns
t _{AW}	Address Valid to End of Write	8	_	10	_	13	_	ns
t _{WP}	Write Pulse Width	8	_	9	_	11	_	ns
t _{WR}	Write Recovery Time	0	_	0	_	0	_	ns
t _{WHZ}	Write to Output High-Z	0	5	0	5	0	5	ns
t _{WLZ}	Write to Output Low Z	3	_	3	_	5	_	ns
t _{DW}	Data Setup to End of Write	5	_	6	_	8	_	ns
t _{DH}	Data Hold from End of Write	0	_	0	_	0	_	ns

Switching Waveforms (Read Cycle)

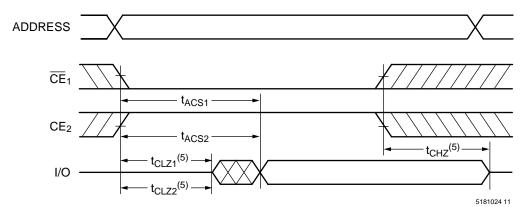
Read Cycle 1^(1, 2)



Read Cycle 2^(1, 2, 4)



Read Cycle 3^(1, 3, 4)



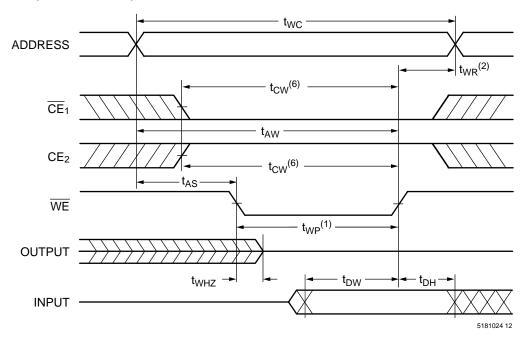
NOTES:

- $\overline{\text{WE}} = V_{\text{IH}}$.
- $\overline{\text{CE}}_1 = \text{V}_{\text{IL}}$ and $\text{CE}_2 = \text{V}_{\text{IH}}$.

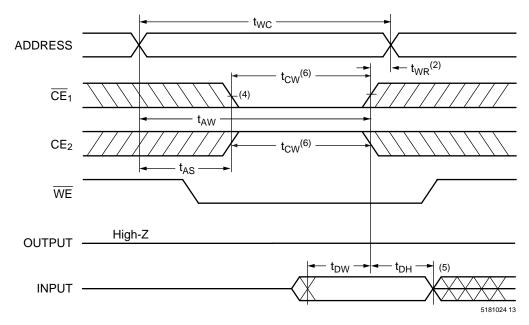
 Address valid prior to or coincident with $\overline{\text{CE}}_1$ transition LOW and/or CE_2 transition HIGH. 3.
- Transition is measured ± 500 mV from steady state with $C_L = 5$ pF. This parameter is guaranteed and not 100% tested.

Switching Waveforms (Write Cycle)

Write Cycle 1 (WE Controlled)(4)



Write Cycle 2 (CE Controlled)⁽⁴⁾



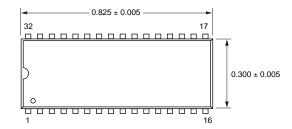
NOTES:

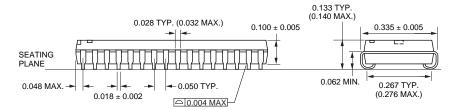
- The internal write time of the memory is defined by the overlap of CE₁ and CE₂ active and WE low. All signals must be active to
 initiate and any one signal can terminate a write by going inactive. The data input setup and hold timing should be referenced to
 the second transition edge of the signal that terminates the write.
- 2. t_{WR} is measured from the earlier of $\overline{\text{CE}}_1$ or $\overline{\text{WE}}$ going high, or CE_2 going LOW at the end of the write cycle.
- 3. During this period, I/O pins are in the output state so that the input signals of opposite phase to the outputs must not be applied.
- 4. $\overline{OE} = V_{IL}$ or V_{IH} . However it is recommended to keep \overline{OE} at V_{IH} during write cycle to avoid bus contention.
- 5. If \overline{CE}_1 is LOW and CE_2 is HIGH during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
- t_{CW} is measured from CE₁ going low or CE₂ going HIGH to the end of write.

Package Diagrams

32-Pin 300 mil SOJ

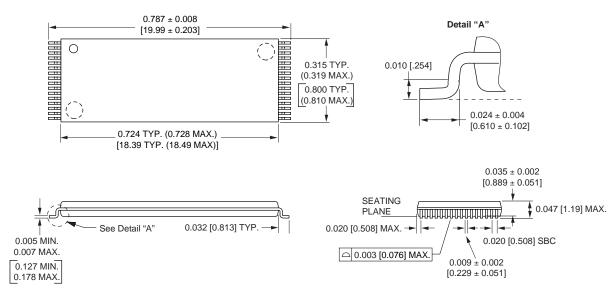
Units in inches





32-Pin TSOP-I

Units in inches [mm]



Notes

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V61C5181024

Notes

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WORLDWIDE OFFICES

V61C5181024

U.S.A.

3910 NORTH FIRST STREET SAN JOSE, CA 95134 PHONE: 408-433-6000 FAX: 408-433-0185

HONG KONG

19 DAI FU STREET TAIPO INDUSTRIAL ESTATE TAIPO, NT, HONG KONG PHONE: 852-2665-4883 FAX: 852-2664-7535

TAIWAN

7F, NO. 102 MIN-CHUAN E. ROAD, SEC. 3 TAIPEI

PHONE: 886-2-2545-1213 FAX: 886-2-2545-1209

1 CREATION ROAD I SCIENCE BASED IND. PARK HSIN CHU, TAIWAN, R.O.C. PHONE: 886-3-578-3344 FAX: 886-3-579-2838

JAPAN

WBG MARINE WEST 25F 6, NAKASE 2-CHOME MIHAMA-KU, CHIBA-SHI CHIBA 261-71

PHONE: 81-43-299-6000 FAX: 81-43-299-6555

IRELAND & UK

BLOCK A UNIT 2 BROOMFIELD BUSINESS PARK MALAHIDE

CO. DUBLIN, IRELAND PHONE: +353 1 8038020 FAX: +353 1 8038049

GERMANY (CONTINENTAL EUROPE & ISRAEL)

71083 HERRENBERG BENZSTR. 32 GERMANY

PHONE: +49 7032 2796-0 FAX: +49 7032 2796 22

U.S. SALES OFFICES

NORTHWESTERN

3910 NORTH FIRST STREET SAN JOSE, CA 95134 PHONE: 408-433-6000 FAX: 408-433-0185

NORTHEASTERN

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CENTRAL & SOUTHEASTERN

604 FIELDWOOD CIRCLE RICHARDSON, TX 75081 PHONE: 972-690-1402 FAX: 972-690-0341

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